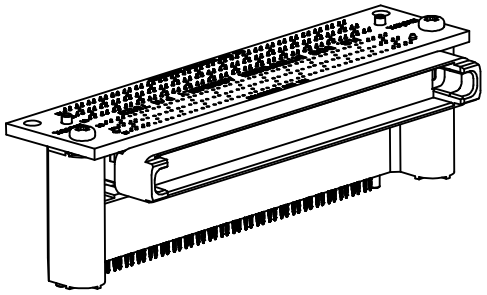
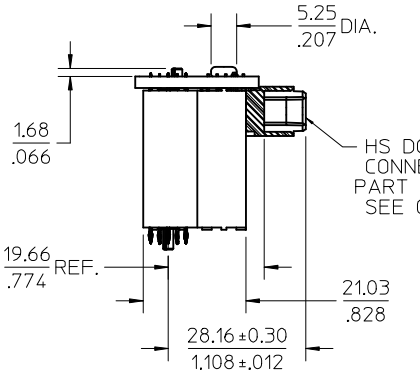
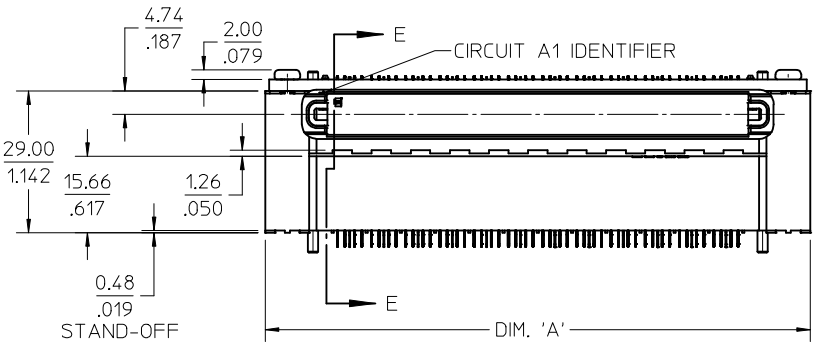
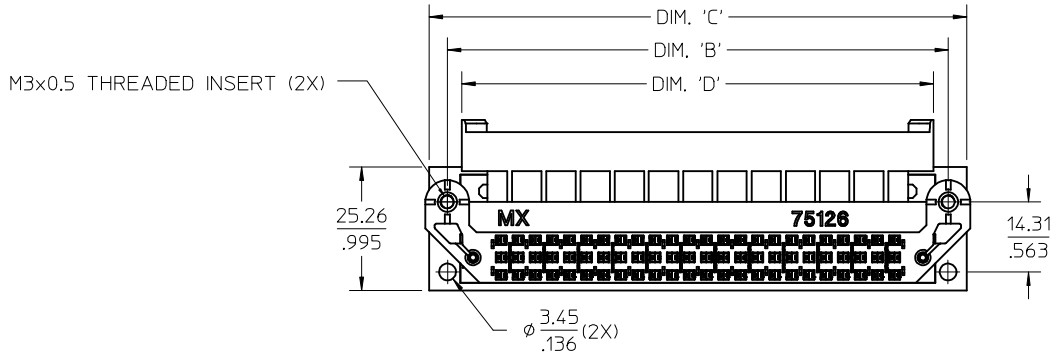
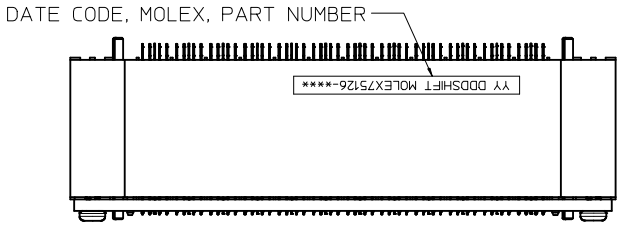




SECTION E-E
(PARTIAL)







NOTES:
1. MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:
   HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED,94V-0.
   WAFER DIELECTRIC: LIQUID CRYSTAL POLYMER (LCP), 94V-0, BLACK.
   CONTACTS: COPPER ALLOY
   HEXAGONAL MACHINE SCREW: CARBON STEEL
2. THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
3. THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
4. THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC PS-45499-002.
5. RECOMMENDED DRILL SIZE: 0.61±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
6. USE APPLICATION TOOL 622020232 WHEN INSERTING INTO PCB.
7. RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THICKNESS MIN. TORQUE REQUIREMENT: 2 IN-LBS MIN. 5 IN-LBS MAX.

CONVERT TO LEAD-FREE
EC NO: UCP2013-1884 2012/11/12
DRWN:TIBARRA
CHKD:
APPR:SMILLER 2013/01/04
DESCRIPTION
Q
REV

QUALITY SYMBOLS
▽=0
▽=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
0 PLACE	±	±

ANGULAR ± 2 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM/IN
SCALE: 2:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY	DSCHMIDG
DATE	02/06/27
CHECKED BY	DSCHMIDG
DATE	2003/03/18
APPROVED BY	MBANAKIS
DATE	2/18/03
MATERIAL NO.	SEE TABLE

TITLE: PLATEAU HS DOCK INTERPOSER SALES DRAWING

molex

DOCUMENT NO. SD-75126-001
SHEET NO. 1 OF 3

SIZE D

CIRCUIT SIZE	ITEM NUMBER	HS DOCK CONNECTOR	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	PLATING OPTION	CONNECTOR WAFER TYPE
108			90.50 3.563	81.50 3.209	89.00 3.504	75.62 2.977	99.40 3.913	71.00±0.08 2.795±.003	66.00±0.08 2.598±.003	FINISH 1	WELDED
144	75126-1003	75018-3021	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-1103	75018-3121	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 2	
144	75126-3003	75018-3121	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-7103	75018-8121	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 3	WELDLESS

1. PLATING FINISH:
   - FINISH 1: (PREVIOUSLY TIN-LEAD)
     - CONTACT INTERFACE
       - 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
       - NICKEL UNDERPLATE OVERALL
     - COMPLIANT INTERFACE
       - 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
       - NICKEL UNDERPLATE OVERALL
     - HOUSING
       - 0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER
       - 3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
       - COPPER UNDERPLATE OVERALL
   - FINISH 2:
     - CONTACT INTERFACE
       - 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
       - NICKEL UNDERPLATE OVERALL
     - COMPLIANT INTERFACE
       - 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
       - NICKEL UNDERPLATE OVERALL
     - HOUSING
       - 0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER
       - 3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
       - COPPER UNDERPLATE OVERALL
   - FINISH 3:
     - CONTACT INTERFACE
       - 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
       - NICKEL UNDERPLATE OVERALL
     - COMPLIANT INTERFACE
       - 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
       - NICKEL UNDERPLATE OVERALL
     - HOUSING
       - 3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
       - COPPER UNDERPLATE OVERALL

SEE SHEET 1
EC NO: UCP2013-1884 2012/11/12
DRWN: I BARRA
CHKD:
APPR: SMILLER 2013/01/04
DESCRIPTION
REV
Q

QUALITY SYMBOLS
▽=0
▽=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	±.010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
0 PLACE	±	±

ANGULAR ± 2 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM/IN
SCALE: 2:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: DSCHMIDG DATE: 02/06/27
CHECKED BY: DSCHMIDG DATE: 2003/03/18
APPROVED BY: MBANAKIS DATE: 2/18/03
MATERIAL NO.: SEE TABLE

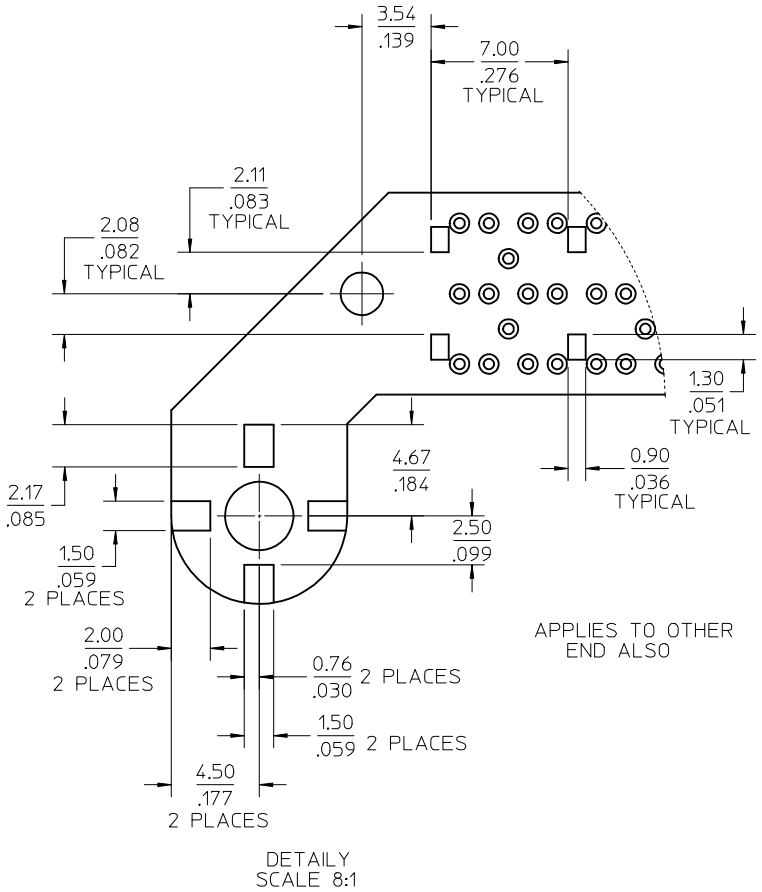
TITLE: PLATEAU HS DOCK INTERPOSER SALES DRAWING

molex

DOCUMENT NO.: SD-75126-001
SHEET NO.: 2 OF 3

SIZE: D

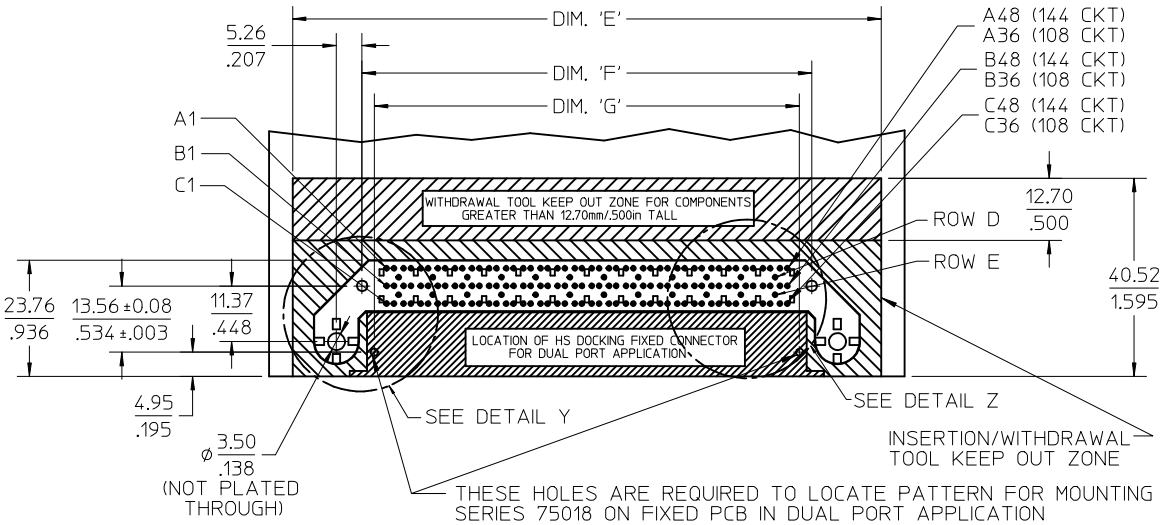
KEEP OUT AREA FOR CONNECTOR STAND-OFFS

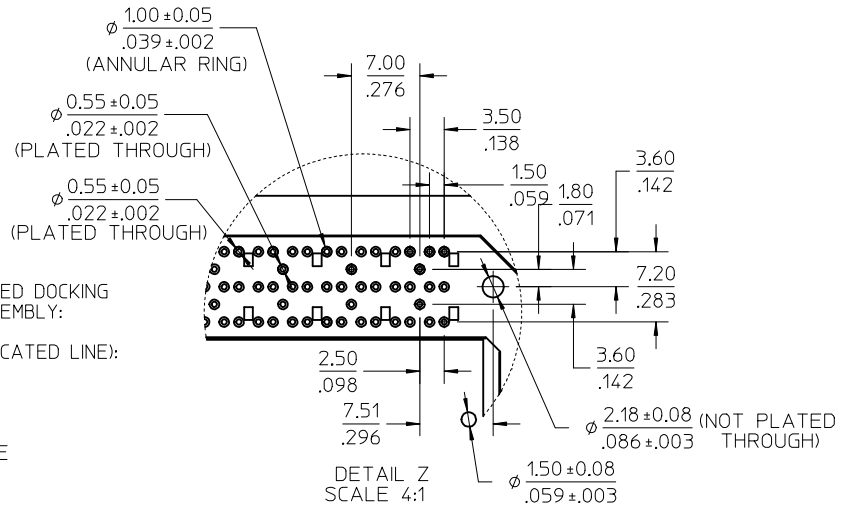


APPLIES TO OTHER END ALSO

DETAILY
SCALE 8:1

NOTE: THE DIMENSION DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.





DETAIL Z
SCALE 4:1

CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:

POWER CIRCUITS (1.5 AMPS PER INDICATED LINE):
A2-A1: POWER/RETURN;
A4-A3: POWER/RETURN;
C2-C1: POWER/RETURN

ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS
CURRENT CAPACITY: 300mA

GROUND CIRCUITS: ROWS D & E

SEE SHEET 1
EC NO: UCP2013-1884 2012/11/12
DRWN: I BARRA
CHKD:
APPR: SMILLER 2013/01/04
DESCRIPTION
REV Q

QUALITY SYMBOLS
▽=0
▽=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
0 PLACE	±	±

ANGULAR ± 2 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

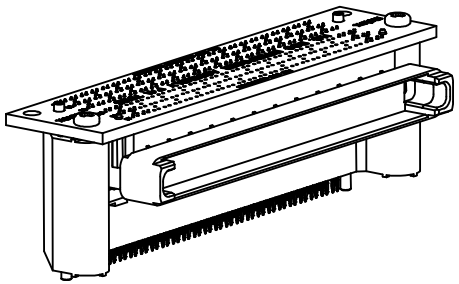
DIMENSION STYLE: MM/IN
SCALE: 1:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

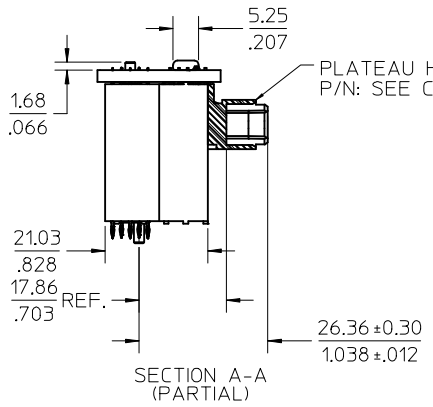
DRAWN BY	DSCHMIDG 02/06/27
CHECKED BY	DSCHMIDG 2003/03/18
APPROVED BY	MBANAKIS 2/18/03
MATERIAL NO.	SEE TABLE

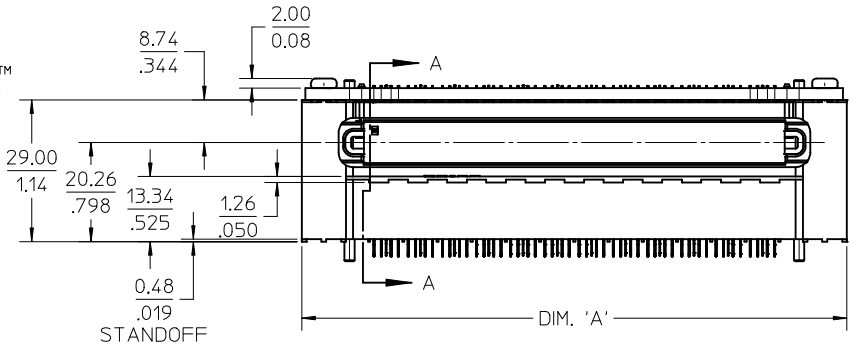
TITLE: PLATEAU HS DOCK INTERPOSER SALES DRAWING

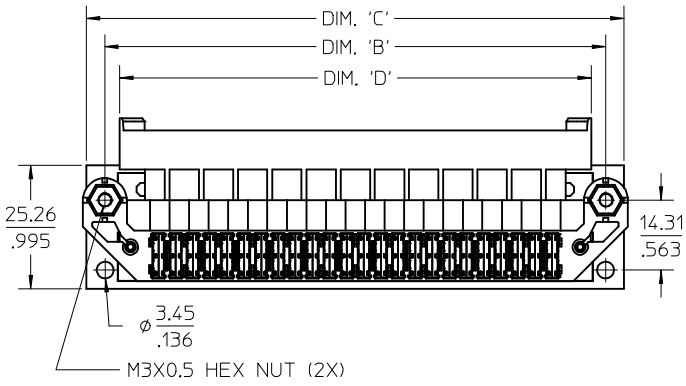
molex

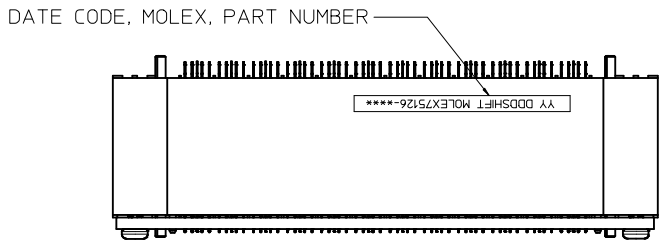
DOCUMENT NO. SD-75126-001
SHEET NO. 3 OF 3
SIZE D











NOTES:
1. MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:
   HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94 V-0.
   WAFER: LIQUID CRYSTAL POLYMER (LCP), 94 V-0, BLACK.
   CONTACTS: COPPER ALLOY
   HEXAGONAL THREADED INSERT: CARBON STEEL
   MACHINE SCREW: CARBON STEEL
2. THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
3. THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
4. THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC. PS-45499-002.
5. RECOMMENDED DRILL SIZE: 0.66±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
6. USE APPLICATION TOOL 62202XXXX WHEN INSERTING INTO PCB.
7. RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THCKNESS MIN. TORQUE REQUIREMENT: 2 IN-LBS MIN. 5 IN-LBS MAX.

CONVERT TO LEAD-FREE
EC NO: UCP2013-1884 2012/11/12
DRWN: I IBARRA 2013/01/04
CHKD:
APPR: MILLER
DESCRIPTION
REV: J3

QUALITY SYMBOLS: ▽=0 ▽=0 ▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
0 PLACE	±	±

ANGULAR ±1/2°
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM/IN
SCALE: 2:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

		DATE
DRAWN BY	KSTILES	7/16/2003
CHECKED BY	DSCHMIDG	7/16/2003
APPROVED BY	MBANAKIS	7/16/2003

TITLE: PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING
molex
MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-75126-002
SHEET NO.: 1 OF 3
SIZE: D

CIRCUIT SIZE	ITEM NUMBER	PLATEAU HS DOCK™	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	PLATING FINISH	CONNECTOR WAFER TYPE
108			90.50 3.563	81.50 3.209	89.00 3.504	75.62 2.977	99.40 3.913	71.00±0.08 2.795±.003	66.00±0.08 2.598±.003	FINISH 1	WELDED
144	75126-2001	75018-3023	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-2101	75018-3123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 2	
144	75126-4001	75018-3123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-8101	75018-8123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 3	WELDLESS

1. PLATING FINISH:
   - FINISH 1: (PREVIOUSLY TIN-LEAD)
     - CONTACT INTERFACE
       - 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
       - NICKEL UNDERPLATE OVERALL
     - COMPLIANT INTERFACE
       - 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
       - NICKEL UNDERPLATE OVERALL
     - HOUSING
       - 0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER
       - 3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
       - COPPER UNDERPLATE OVERALL
   - FINISH 2:
     - CONTACT INTERFACE
       - 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
       - NICKEL UNDERPLATE OVERALL
     - COMPLIANT INTERFACE
       - 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
       - NICKEL UNDERPLATE OVERALL
     - HOUSING
       - 0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER
       - 3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
       - COPPER UNDERPLATE OVERALL
   - FINISH 3:
     - CONTACT INTERFACE
       - 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
       - NICKEL UNDERPLATE OVERALL
     - COMPLIANT INTERFACE
       - 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
       - NICKEL UNDERPLATE OVERALL
     - HOUSING
       - 3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
       - COPPER UNDERPLATE OVERALL

SEE SHEET 1
EC NO: UCP2013-1884 2012/11/12
DRWN: I BARRA
CHKD:
APPR: SMILLER 2013/01/04
DESCRIPTION
REV
J3

QUALITY SYMBOLS
▽7 =0
▽6 =0
▽5 =0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
0 PLACE	±	±

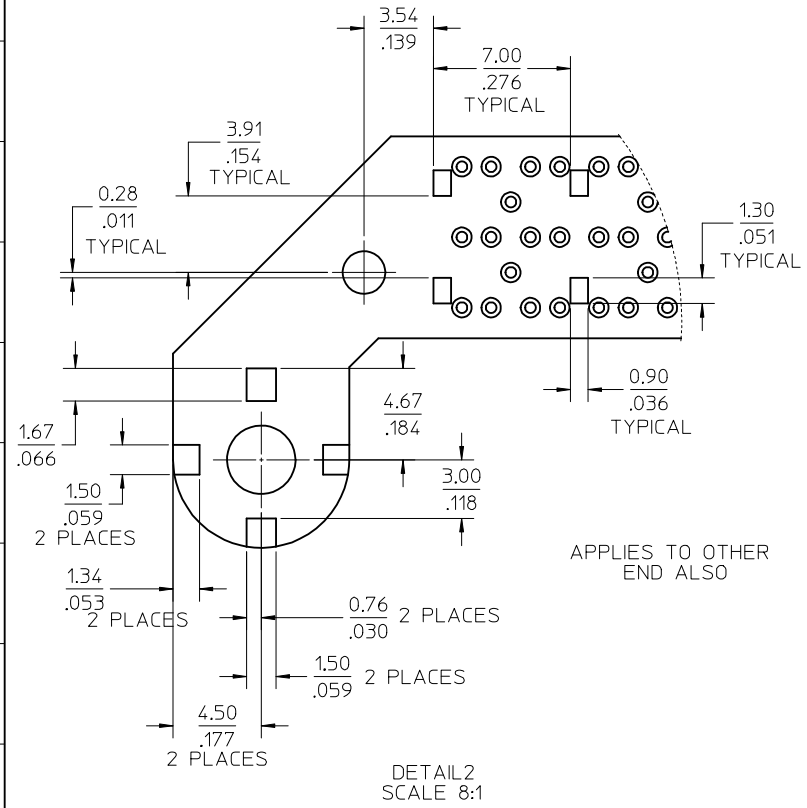
ANGULAR ±1/2°
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM/IN
SCALE: 2:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

		DATE
DRAWN BY	KSTILES	7/16/2003
CHECKED BY	DSCHMIDG	7/16/2003
APPROVED BY	MBANAKIS	7/16/2003

TITLE: PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING
molex
MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-75126-002
SHEET NO.: 2 OF 3
SIZE: D

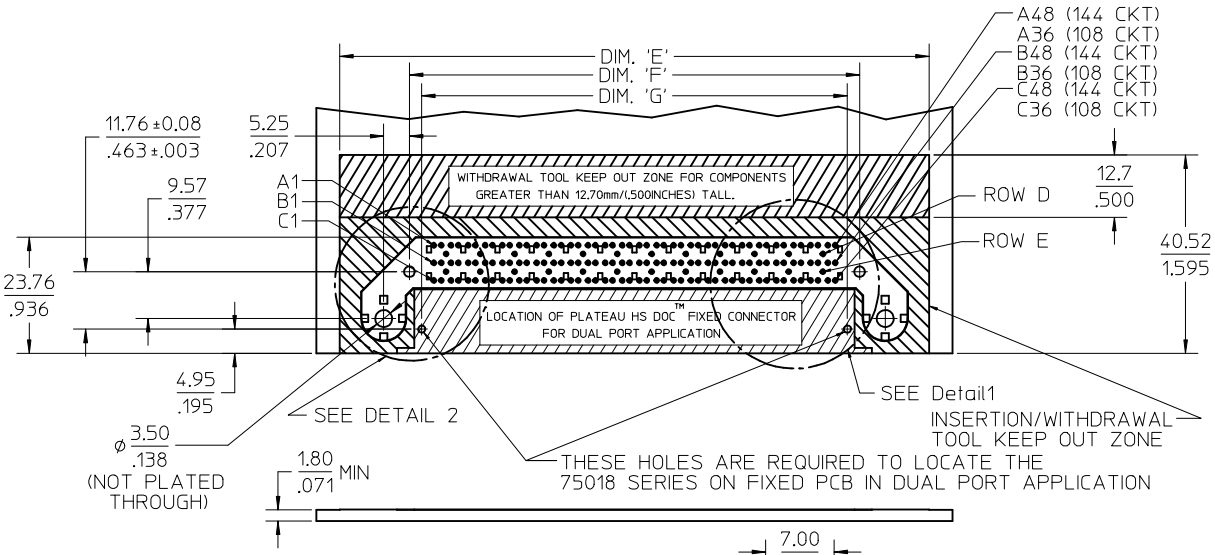
KEEP OUT AREA FOR STAND-OFFS

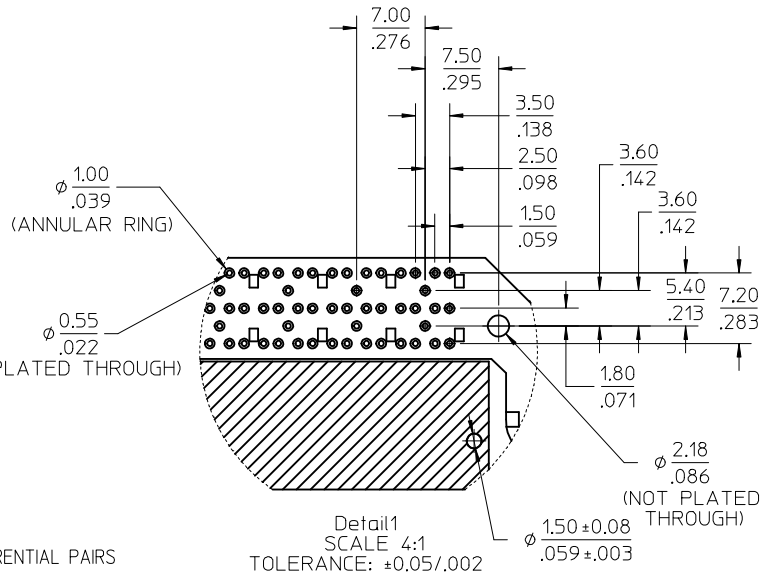


APPLIES TO OTHER END ALSO

DETAIL2
SCALE 8:1

NOTE: THE DIMENSIONS DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.





Detail1
SCALE 4:1
TOLERANCE: ±0.05/.002

CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:

POWER CIRCUITS (1.5 AMPS PER INDICATED LINE):
A2-A1: POWER/RETURN,
A4-A3: POWER/RETURN,
C2-C1: POWER/RETURN

ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS
CURRENT CAPACITY: 300mA

GROUND CIRCUITS: ROWS D & E

SEE SHEET 1
EC NO: UCP2013-1884 2012/11/12
DRWN:T.IBARRA 2013/01/04
CH'KD:
APPR:SMILLER
DESCRIPTION
REV
J3

QUALITY SYMBOLS
=0 4 PLACES
=0 3 PLACES
=0 2 PLACES
=0 1 PLACE
=0 0 PLACE

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
0 PLACE	±	±

ANGULAR ±1/2°
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM/IN
SCALE	2:1
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY	KSTILES
DATE	7/16/2003
CHECKED BY	DSCHMIDG
DATE	7/16/2003
APPROVED BY	MBANAKIS
DATE	7/16/2003
MATERIAL NO.	SEE TABLE
TITLE	PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING
DOCUMENT NO.	SD-75126-002
SHEET NO.	3 OF 3
SIZE	D

molex